**Power Semiconductor Machining Technology** 

# SiC,GaN Machining Technology Exihibition 2025

Exhibition Guideline

# 2025. March 5 [WED] > 7 [FRI] MAKUHARI MESSE

Organizers / JAPAN INDUSTRIAL PUBLISHING CO., LTD. Sankei Shimbun Co., Ltd.

www.sicgan-expo.jp

# Introduction

The "SiC,GaN Machining Technology Exhibition 2025" will be held concurrently with "Grinding Technology Japan 2025," an exhibition specializing in grinding technology. To realize a carbon-neutral society by 2050, it is essential to promote electrification of the mobility industry (EV) as well as the usage of renewable energy as a main power source, and the spread of highly-developed power electronics technology using advanced power semiconductors such as SiC and GaN has become the most important factor. Therefore, mass production and cost reduction of advanced power semiconductor wafers are strongly desired. However, these materials are extremely hard and resistant to heat

and chemicals. Processing them is extremely time-consuming, and reducing the high processing cost is an urgent issue.

"SiC,GaN Machining Technology Exihibition 2025" is an exhibition for engineers and technicians involved in the processing of these advanced power semiconductor wafers, as well as for advanced power semiconductor researchers and those who wish to learn more about them. We believe that exhibitors will be able to provide the best answers with the latest technology and knowledge to visitors with such issues. "SiC,GaN Machining Technology Exihibition 2025" will feature slicing, grinding, polishing, and CMP processing technologies related to advanced power semiconductor wafer processing, as well as a variety of wafer evaluation technologies.

"SiC,GaN Machining Technology Exihibition 2025" will be participated in by the Japan Society for Abrasive Technology, which focuses its research on abrasive grain processing, and the Japan Society for Applied Physics Advanced Power Semiconductors, which focuses on advanced power semiconductors such as SiC, GaN, and diamond, as "special cooperation" organizations.

There is no argument that in addition to technology and skills, theoretical underpinnings are important for advancing advanced power semiconductor wafer processing. At the "SiC,GaN Machining Technology Exhibition 2025," the Japan Society for Abrasive Technology and other cooperating organizations will provide explanations of processing theory from an academic standpoint and talk about the future of semiconductor wafer processing technology.

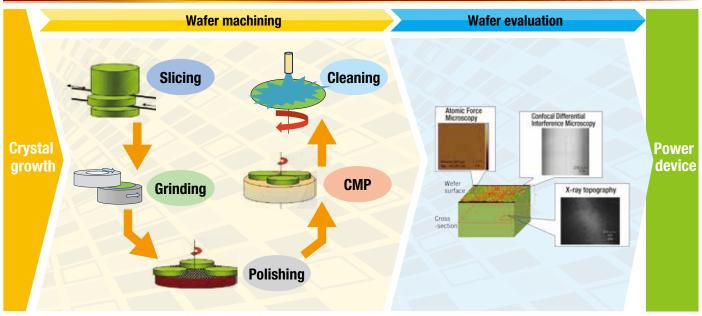
# Outline

Title Organizers	SiC,GaN Machining Technology Exihibition 2025 JAPAN INDUSTRIAL PUBLISHING CO., LTD. Sankei Shimbun Co., Ltd.
Date	March 5 (Wed.) - 7 (Fri.), 2025 (3 days held biennially)
Venue	Makuhari Messe, Hall 7-8
Admission	Free for holders of invitation card or with pre-registration
<b>Collaborating Organization</b>	The Japan Society for Abrasive Technology / The Japan Society for Applied Physics Advanced Power Semiconductors
Exhibition Subjects	SiC / GaN Ingot Slicing Machine, SiC / GaN Wafer Grinding Machine, SiC / GaN Grinding Stones, Wafer Beveling Machine, SiC / GaN Single/Double-Side Lapping Machine, SiC / GaN Chemical, Mechanical Polishing Machine, CMP Slurries for SiC / GaN, Wafer Cleaning System, Wafer Shape Measuring Machine
Visitors Categories	Engineer / Researcher of Bulk Single Crystal Growth for SiC/GaN, Engineer / Researcher of Wafer Processing Technology for SiC/GaN, Engineer / Researcher for Diamond Wafers, Engineer / Researcher of Wafer Evaluation Technology, Students etc.

#### Held at the same time Grinding Technology Japan 2025

Exhibition Subjects
Grinding machines, Polishing machines, Grinding wheels, Truing machines, Precision measuring devices, Peripheral devices, Tool Grinding machines, Cutting tools, Cutt

# SiC,GaN Machining Technology Exhibition Image

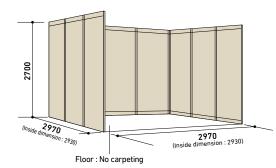


## **Application Deadline** September 30th, 2024

# **Booth Specifications and Exhibition Fee**

#### **Booth specifications**

1 booth - unit (width 3 m × depth 3 m × height 2.7 m)



The basic booth shall be set up according to system panel specifications, and the rear and side walls shall be installed by the organizer.

#### **Exhibition fee**

Exhibition fee (per booth)

### Layout of booths

The booths can be arranged in five ways - row, block, island (double), island (triple), - to suit the exhibits, the method of installing the booths and special arrange booths.

1-9 booths can decorate the booth to a height of 4.0 m. (a one-meter setback from the passage and from the basic panel can accommodate a decoration of up to 3.6 meters.)

In addition, exhibitors who use an island booth consisting of at least 10 booths can decorate the booth to a height of 5 m.

> Block (double) booths At least 4 booths

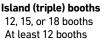
#### Row type



Island (double) booth At least 10 booths



418,000 yen (including tax)





Special arrange booths At least 20 booths (180m<sup>2</sup>)



# **Turnkey Booth Package**

A simple and quick booth package plan is available

Parapet, reception counter, carpet, lighting (fluorescent 20 W × 1 light, spotlights  $15W \times 2$  lamps), 1 foldable chair, business card drop-box imes 1, company name display, brochure stand (A4 size / 12 shelf), electric power use up to 1 kW included (higher power consumption charged separately) usage fees, outlet imes 1.

Exhibition fee + 158,400 yen (including tax)



# **Exhibitor Presentation**

Exhibitor Presentation provides exhibitors with opportunities to introduce their products and the latest technologies at the conference room provided in the exhibition hall. Inviting your prospective customers to the presentation is obviously an excellent way of not only introducing your products or technologies, but also promoting your corporate image for many visitors.

Participation Fee : 1 session (45 minutes)	55,000 yen (including tax)
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\*For further details and application, please visit the official website.

# Web Banner

#### Highlight your presence beforehand with a Link Banner on our Official Website

Dates:	From February 5 to April 7, 2025 [TBC]
Publishing fee:	<b>55,000 yen</b> (including tax)
Banner size:	W200px × H40px GIF format (can be animated)
Data reception deadline:	January 17, 2025 $st$ for final version data at the above size

# Schedule

Sptember 30 (Mon.), 2024	Application Deadline
Early December 2024	Release of the Floor Plan and Exhibitor Manual * The Exhibitor Manual includes application forms for display package equipmer electricity. etc.
During December 2024	Dispatch of Invitation cards % We will send the requested amount of Invitation cards for free (Invitation cards in English will be available in PDF only.)
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Middle January 2025	Deadline for diverse services (Electricity, Rental fumiture, etc.) % All application forms will be enclosed in the Exhibitor Manual.
March 2 (Sun.) - March 4 (Tue.), 2025	Booth construction, decoration setting-up
March 5 (Wed.) – 7 (Fri.), 2025	Exhibition
March 7 (Fri.), 2025	Removal (17:00 - 21:00)
8 (Sat.)	Removal (9:00 - 17:00)
May, 2025	Exhibition Report

# Access

## **MAKUHARI MESSE**

2-1, Nakase, Mihama-ku, Chiba-shi, Chiba 261-8550, Japan Phone : +81-43-296-0001

#### https://www.m-messe.co.jp/en/



### By public transportation

#### By Train

- Approx. 30 minutes from Tokyo Station or 12 minutes from Soga Station to Kaihim Makuhari Station on the JR Keiyo Line. 5 minutes walk to Makuhari Messe.
- Approx. 40 minutes from Akihabara Station to Makuhari Hongo Station on the JR Sobu Line. 15 minutes by bus to Makuhari Messe.

#### By Bus

 Limousine Bus services from both Tokyo international Airport (Haneda) and Narita International Airport are available.



